

Title (en)

METAL PLATE, MASK FOR DEPOSITION AND MANUFACTURING METHOD THEREFOR

Title (de)

METALLPLATTE, MASKE ZUR ABSCHIEDUNG UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

PLAQUE MÉTALLIQUE, MASQUE POUR UN DÉPÔT ET PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication

EP 3419074 B1 20210414 (EN)

Application

EP 17753392 A 20170131

Priority

- KR 20160017682 A 20160216
- KR 20160040436 A 20160401
- KR 2017001043 W 20170131

Abstract (en)

[origin: EP3419074A1] A metal plate for use in the manufacture of a mark for deposition according to an embodiment comprises: an outer layer defined by a thickness of 1 μ m or less from a surface of the metal plate; and an inner layer other than the outer layer, wherein an etch rate of the outer layer is slower than an etch rate of the inner layer, and wherein the etch rate of the outer layer is 0.03 μ m/sec or less and the etch rate of the inner layer is 0.03 to 0.05 μ m/sec, when measured under the etching conditions at 45°C with an etchant containing 35-45 wt% of FeCl₃.

IPC 8 full level

C23F 1/02 (2006.01); **C21D 6/00** (2006.01); **C21D 8/02** (2006.01); **C21D 9/46** (2006.01); **C22C 38/08** (2006.01); **C23C 14/04** (2006.01); **C23F 1/04** (2006.01); **C23F 1/28** (2006.01); **G03F 7/00** (2006.01); **H10K 99/00** (2023.01)

CPC (source: CN EP)

C22C 38/08 (2013.01 - EP); **C23C 14/042** (2013.01 - CN EP); **C23F 1/02** (2013.01 - EP); **C23F 1/04** (2013.01 - EP); **C23F 1/28** (2013.01 - EP); **H10K 71/00** (2023.02 - CN); **H10K 71/166** (2023.02 - CN); **C21D 6/001** (2013.01 - EP); **C21D 8/0205** (2013.01 - EP); **C21D 9/46** (2013.01 - EP); **C21D 2201/05** (2013.01 - EP); **G03F 7/0015** (2013.01 - EP); **H10K 71/166** (2023.02 - EP)

Cited by

EP4019660A3; US11976349B2; US10727409B2; US11335854B2; US11732364B2; US11795549B2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 3419074 A1 20181226; **EP 3419074 A4 20190320**; **EP 3419074 B1 20210414**; CN 108701776 A 20181023; CN 108701776 B 20200922; CN 112103403 A 20201218; CN 112103403 B 20230905; JP 2019507829 A 20190322; JP 7072512 B2 20220520; WO 2017142231 A1 20170824

DOCDB simple family (application)

EP 17753392 A 20170131; CN 201780011646 A 20170131; CN 202010848326 A 20170131; JP 2018542774 A 20170131; KR 2017001043 W 20170131